



CSP-75 Lead Free RoHS Profile

Total Mass of the Unit specified (g)	Product / Component Description	Breakdown of product / component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass (mg)	PPM	Additional Information
0.052	75 Ball CSP	IC Chip	Silicon doped with aluminium	Silicon (Si)	7440-21-3	36.445344	705,685	
		IC Chip	Silicon doped with aluminium	Aluminium (Al)	7429-90-5	0.021778	422	
		Metalization	UBM	Aluminium (Al)	7429-90-5	0.013525	262	
		Metalization	UBM	Nickel (Ni)	7440-02-0	0.006763	131	
		Metalization	UBM	Vanadium (V)	7440-62-2	0.006763	131	
		Metalization	UBM	Copper (Cu)	7440-50-8	0.053872	1,043	
		Metalization	BCB			0.081840	1,585	Cyclotene 4022-35
		IC Solderball	Solderball	Tin (Sn)	7440-31-5	14.339891	277,661	
		IC Solderball	Solderball	Silver (Ag)	7440-22-4	0.600543	11,628	
		IC Solderball	Solderball	Copper (Cu)	7440-50-8	0.075000	1,452	

Total mass (mg)	51.645
-----------------	--------